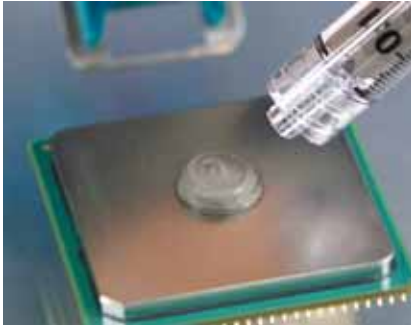


High Performance, Value Compound for High-End Computer Processors

Features and Benefits

- High thermal performance: 0.32°C/W (@ 50 psi)
- Good screenability
- Room temperature storage
- No post “cure” required
- Exceptional value



TIC 1000A is a high performance, thermally conductive compound intended for use as a thermal interface material between a high-end computer processor and a heat sink. Other high watt density applications will also benefit from the extremely low thermal impedance of TIC 1000A.

TIC 1000A compound wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The compound requires pressure of the assembly to cause flow. The TIC 1000A compound will resist dripping.

For microprocessor applications, traditional screw fastening or spring clamping methods will provide adequate force to optimize the thermal performance of TIC 1000A.

An optimized application would utilize the minimum volume of TIC 1000A material necessary to ensure complete wet-out of both mechanical interfaces.

Assembly – No Post Screen Cure

TIC 1000A has good screenability. No solvent is used to reduce the viscosity, so no post “cure” conditioning is required.

TYPICAL PROPERTIES OF TIC 1000A

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Gray	Gray	Visual			
Density (g/cc)	2.1	2.1	ASTM D792			
Continuous Use Temp (°F) / (°C)	302	150	—			
ELECTRICAL						
Electrical Resistivity (Ohm-meter) (1)	N/A	N/A	ASTM D257			
THERMAL						
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470			
THERMAL PERFORMANCE vs PRESSURE						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W) (2)		0.32	0.32	0.32	0.31	0.28

1) The compound contains an electrically conductive filler surrounded by electrically non-conductive resin.
2) TO-220 performance data is provided as a reference to compare material thermal performance.

Application Cleanliness

1. Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC 1000A.

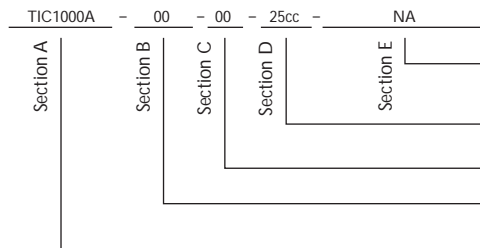
Application Methods

1. Dispense and/or screenprint TIC 1000A compound onto the processor or heat sink surface like thermal grease (see a Bergquist Representative for application information).
2. Assemble the processor and heat sink with spring clips or constant-pressure fasteners.

Typical Applications Include:

- High performance CPUs
- High performance GPUs

Building a Part Number



Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 5cc = 5.0cc, 25cc = 25.0cc, 200cc = 200.0cc, 800cc = 800.0cc, 1600cc = 1600.0cc

00 = No options

00 = No options

TIC1000A = Thermal Interface Compound 1000A
TIG1000A = Thermal Interface Gel 1000A

Note: To build a part number, visit our website at www.bergquistcompany.com.



Henkel Bergquist Preferred Converter

10135 Gottschalk Parkway
Chagrin Falls, Ohio 44023
sales@rico-inc.com
+1 440-543-9209

All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND FITNESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using, user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NEITHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER IN TORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARISING OUT OF THE USE OR THE INABILITY TO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer.
PDS_TIC_1000A_0207